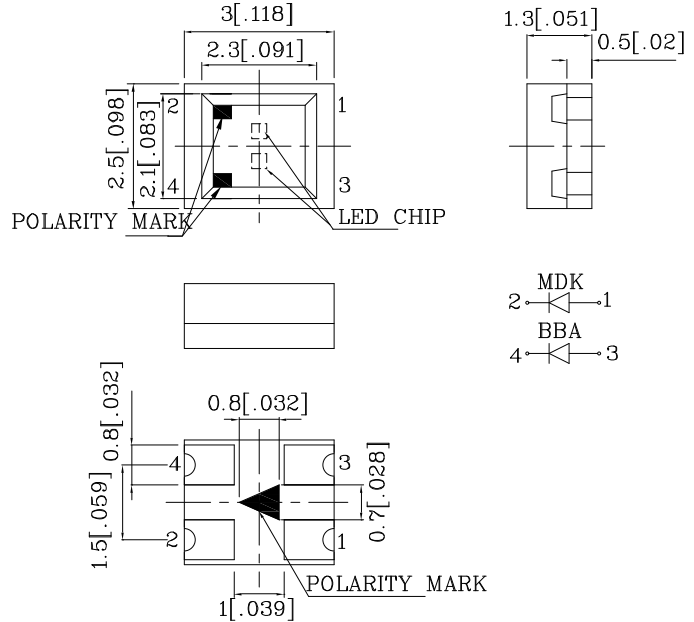


PRELIMINARY SPEC

Features

- 3.0mmx2.5mm SMT LED, 1.3mm THICKNESS.
- BI -COLOR,LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



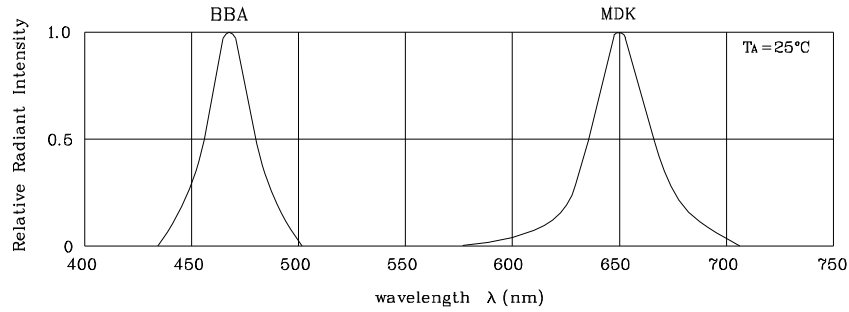
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. Specifications are subject to change without notice.

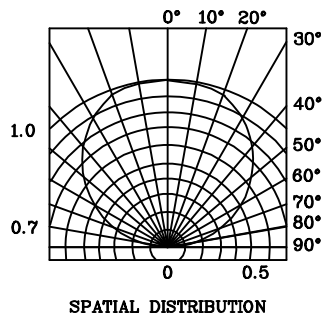
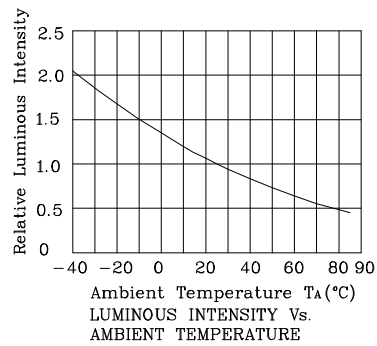
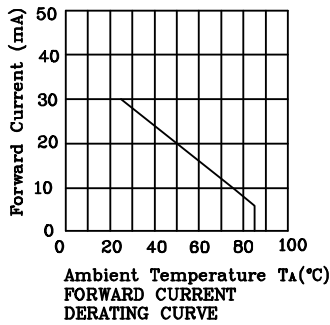
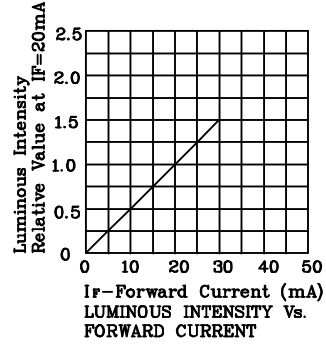
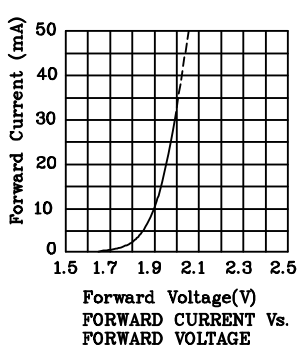
Absolute Maximum Ratings (TA=25°C)		MDK (InGaA IP)	BBA (InGaN)	Unit
Reverse Voltage	V _R	5	5	V
Forward Current	I _F	30	30	mA
Forward Current (Peak) 1/10Duty Cycle 0.1ms Pulse Width	i _{FS}	185	100	mA
Power Dissipation	P _T	75	120	mW
Electrostatic Discharge Threshold (HBM)		-	1000	V
Operating Temperature	T _A	-40 ~ +85		°C
Storage Temperature	T _{stg}	-40 ~ +85		

Operating Characteristics (TA=25°C)		MDK (InGaA IP)	BBA (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V _F	1.95	3.2	V
Forward Voltage (Max.) (I _F =20mA)	V _F	2.5	4.0	V
Reverse Current (Max.) (V _R =5V)	I _R	10	10	μA
Wavelength Of Peak Emission (Typ.) (I _F =20mA)	λ _P	650	468	nm
Wavelength Of Dominant Emission (Typ.) (I _F =20mA)	λ _D	635	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	28	21	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	35	100	pF

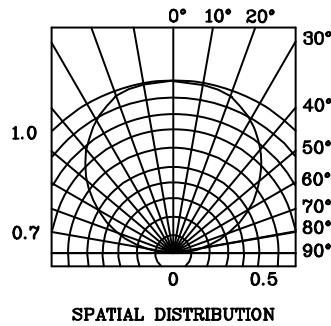
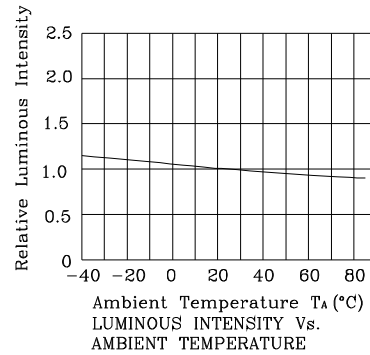
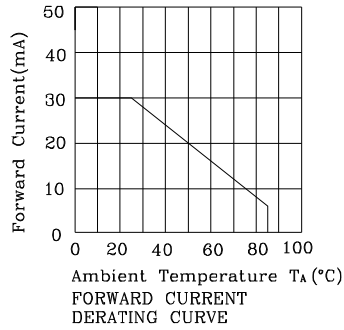
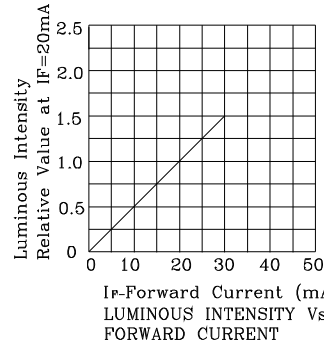
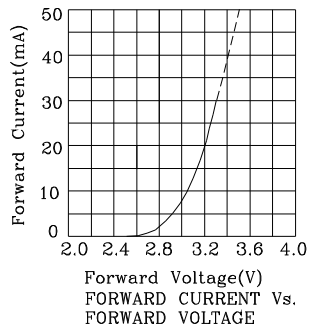
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λ _P	Viewing Angle 2 θ 1/2
				min.	typ.		
ZMDKBBA70W	Red	InGaAlP	Water Clear	70	148	650	120°
	Blue	InGaN		18	59	468	



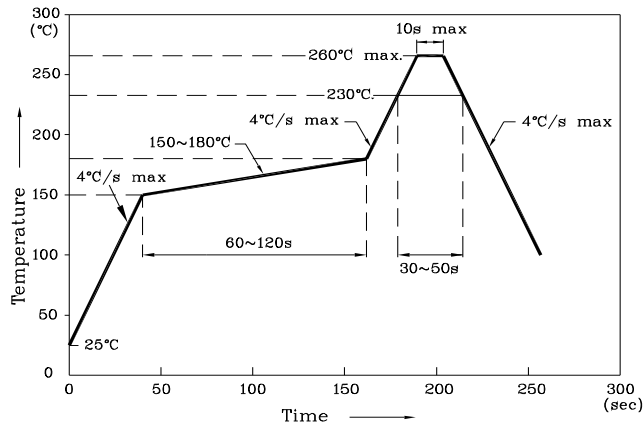
❖ **MDK**



❖ **BBA**



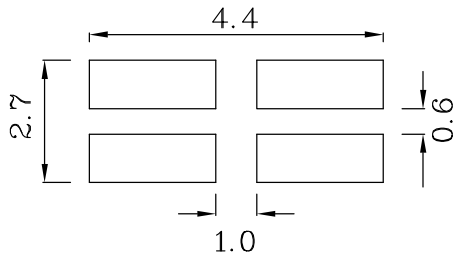
Reflow Soldering Profile For Lead-free SMT Process.



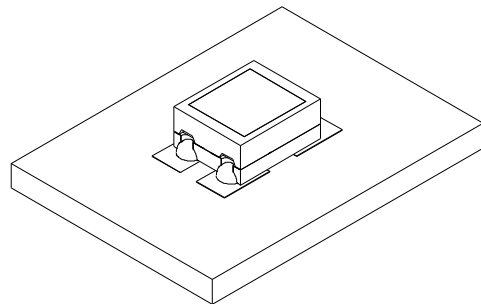
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C–260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

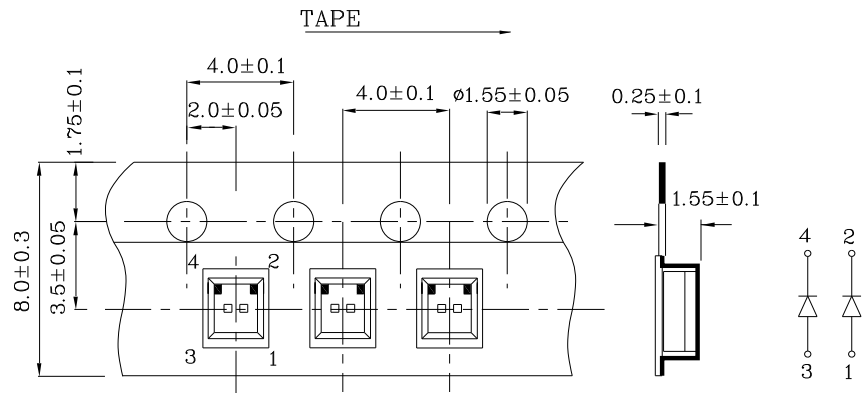
❖ Recommended Soldering Pattern
(Units : mm; Tolerance: ± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

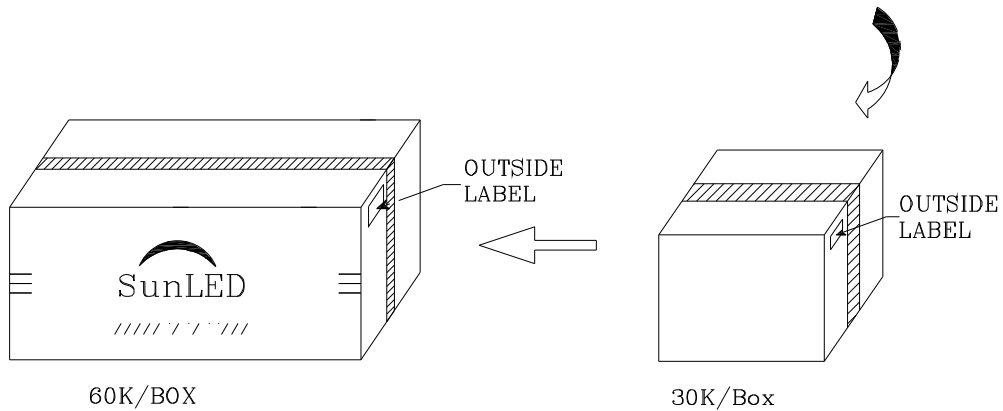
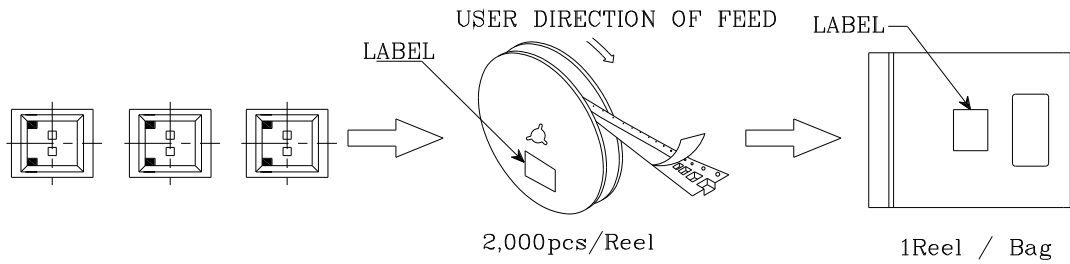
1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V


Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS

ZMDKBBA70W



P/NO : Zxxx70x	
QTY : 2,000 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 XXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	